501883671 04/10/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsu-Shun CHEN	04/29/2010
Cheng Hung LEE	04/29/2010
Chung-Hi LU	04/30/2010
Hong-Chen CHENG	04/29/2010
Chung-Yi WU	04/29/2010
Chih-Chieh CHIU	04/29/2010

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13443619

CORRESPONDENCE DATA

 Fax Number:
 (703)518-5499

 Phone:
 7036841111

 Email:
 tsmc@ipfirm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	T5057-Y169B

REEL: 028022 FRAME: 0119

PATENT

501883671

NAME OF SUBMITTER:	Randy A. Noranbrock
Total Attachments: 2 source=efiledassgn#page1.tif source=efiledassgn#page2.tif	

PATENT REEL: 028022 FRAME: 0120

Docket No. T5057-Y169A

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

Hsu-Shun CHEN 4) Hong-Chen CHENG 1) 5) Chung-Yi WU Cheng Hung LEE Chih-Chieh CHIU Chung-Hi LU 6

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD, having a place of business at No.

8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu, Taiwan 300, R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MULTI-POWER DOMAIN DESIGN

for which an application for United States Letters Patent was filed on February 19, 2010 , and identified by (a) United States Patent Application No. 12/708,923 ; or (b) for which an application for United States Letters Patent was executed on ______

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

Date:

5) Chang Yi Wa	2010.04.29
Name: Chung-Yi WU	Date;
6) Chih Chiel Chin	>010 04.29
Name: Chih-Chieh CHIU	Date:

PATENT REEL: 028022 FRAME: 0122

RECORDED: 04/10/2012